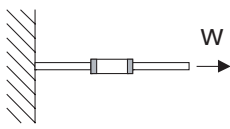
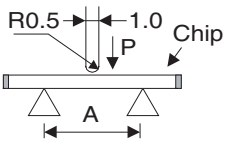


■ PERFORMANCE TESTS

TEST	SPECIFICATION	TEST CONDITION		
Solderability	* More than 90% of the terminal electrode will be covered with fresh solder.	Solder Temperature: 240 ± 5°C		
Soldering Heat Resistance	* The chip will not crack. * More than 75% of the terminal electrode will be covered with solder.	Solder Temperature: 255 ± 5°C Dip Time: 3 ± 1 Seconds		
Terminal Strength	* The terminal electrode will not break and the ceramic will not be damaged. 	TYPE	KGF	Time(sec)
		HFI-160808	0.2	10±5
		HFI-201209	0.6	30±5
Bending Strength	* The body shall not be damaged by force. 	TYPE	A(mm)	KGF
		HFI-100505	0.4	0.6
		HFI-160808	1.0	0.6
HFI-201209	1.4	1.0		

■ CLIMATIC TESTS

TEST	SPECIFICATION	TEST CONDITION		
Thermal Shock (Temperature Cycle)	* There shall be no mechanical damage. * Inductance shall be within 5% of the initial value.	* Temperature: -40°C then 85°C for 30 minutes each. * Total Cycles: 100		
Humidity Resistance	* Q-value shall be within 30% of the initial value.	* Temperature: 60°C * Humidity: 95% RH * Time: 1000 ± 12 hours		
High Temperature Resistance		* Temperature: 85°C ± 2°C * Time: 1000 ± 12 hours		
Low Temperature Resistance		* Temperature: -40°C ± 2°C * Time: 1000 ± 12 hours		

NOTE: Operating Temperature Range: -55°C TO +125°C

Storage Condition: The temperature should be within -40°C To +85°C and humidity should be less than 75%RH. The product should be used within 6 months from the time of delivery.